

AMENDMENTS TO THE CLAIMS

1. (Currently amended) An electronic circuit device comprising:
an electronic component having a connection terminal on one side thereof;
a circuit board made of a polymeric resin sheet and having an electrode pad thereon;
an adhesive sheet having a through-hole, ~~with a cross-sectional area of said electrode pad~~
~~being greater than a cross-sectional area of said through-hole;~~ and
a conductive adhesive ~~provided~~ filled in said through-hole;
wherein said electronic component and said circuit board are bonded to each other via
said adhesive sheet, and said connection terminal on said electronic component and said
electrode pad on said circuit board are bonded to each other by said conductive adhesive filled in
said through-hole, and
wherein a cross-sectional size of said connection terminal is less than a
corresponding cross-sectional size of said through-hole, and said corresponding cross-sectional
size of said through-hole is less than a corresponding cross-sectional size of said electrode pad.

2. (Currently amended) The electronic circuit device according to claim 1, wherein
~~at least one of said connection terminal and said electrode pad~~ protrudes into said through-hole.

3. *(Canceled)*

4. (Currently amended) The electronic circuit device according to claim ~~3~~ 1,
wherein said polymeric resin sheet is made of a material selected from the group consisting of
polyethylene terephthalate, acrylonitrile-butadiene-styrene, polycarbonate, and polyimide.

5. (Previously presented) The electronic circuit device according to claim 1, wherein
said conductive adhesive is a conductive paste consisting essentially of conductive particles and a
thermosetting resin binder.

6. (Previously presented) The electronic circuit device according to claim 1, wherein said adhesive sheet is one of a thermosetting resin sheet and a thermoplastic resin sheet.

7. (Previously presented) The electronic circuit device according to claim 1, wherein said conductive adhesive essentially consists of conductive particles and a thermosetting resin binder, and said adhesive sheet includes a thermosetting resin, with said thermosetting resin being such that it begins to cure at a lower temperature than does said thermosetting resin binder.

8. (Withdrawn) A method of manufacturing an electronic circuit device, comprising:
bonding an adhesive sheet to a circuit board so that a through-hole, through said adhesive sheet, is aligned with an electrode pad provided on a surface of said circuit board;
providing a conductive adhesive in said through-hole; and
bonding a connection terminal, provided on one side of an electronic component, to said electrode pad on said circuit board via said conductive adhesive in said through-hole, and bonding said electronic component to said adhesive sheet.

9. (Withdrawn) The method according to claim 8, wherein said adhesive sheet is one of a thermosetting resin sheet and a thermoplastic resin sheet.

10. (Withdrawn) The method according to claim 8, wherein said conductive adhesive consists essentially of conductive particles and a thermosetting resin binder, and said adhesive sheet includes a thermosetting resin, with said thermosetting resin being such that it begins to cure at a lower temperature than does said thermosetting resin binder.

11. (New) The electronic circuit device according to claim 1, wherein said corresponding cross-sectional size of said electrode pad is more than twice as large as said cross-sectional size of said connection terminal.

12. (New) The electronic circuit device according to claim 1, wherein
said circuit board is made of a polymeric resin sheet selected from the group consisting of
a polyethylene terephthalate resin sheet, an acrylnitrile-butadiene-styrene resin sheet, a
polycarbonate resin sheet, and a polyimide resin sheet.